

To all our customers

Regarding the change of names mentioned in the document, such as Mitsubishi Electric and Mitsubishi XX, to Renesas Technology Corp.

The semiconductor operations of Hitachi and Mitsubishi Electric were transferred to Renesas Technology Corporation on April 1st 2003. These operations include microcomputer, logic, analog and discrete devices, and memory chips other than DRAMs (flash memory, SRAMs etc.) Accordingly, although Mitsubishi Electric, Mitsubishi Electric Corporation, Mitsubishi Semiconductors, and other Mitsubishi brand names are mentioned in the document, these names have in fact all been changed to Renesas Technology Corp. Thank you for your understanding. Except for our corporate trademark, logo and corporate statement, no changes whatsoever have been made to the contents of the document, and these changes do not constitute any alteration to the contents of the document itself.

Note : Mitsubishi Electric will continue the business operations of high frequency & optical devices and power devices.

Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

3812 Group

SINGLE-CHIP 8-BIT CMOS MICROCOMPUTER

DESCRIPTION

The 3812 group is the 8-bit microcomputer based on the 740 family core technology.

The 3812 group has six 8-bit timers, and an 8-channel A-D converter as additional functions.

The various microcomputers in the 3812 group include variations of internal memory size and packaging. For details, refer to the section on part numbering.

FEATURES

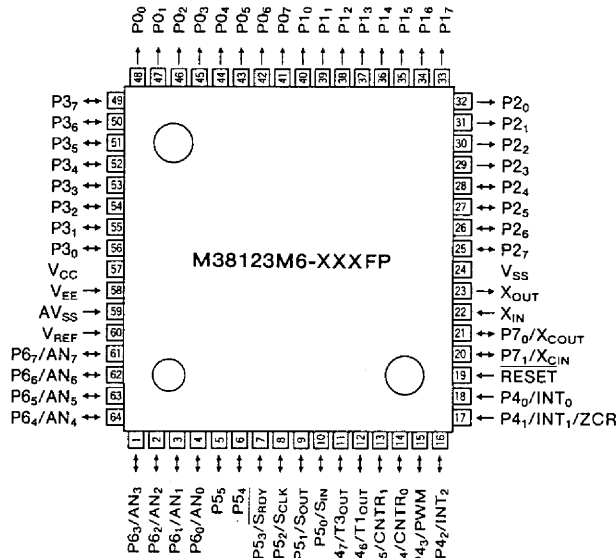
- Basic machine-language instructions 71
- The minimum instruction execution time 0.63 μ s
(at 6.3MHz oscillation frequency)
- Memory size
- ROM 4K to 60K bytes
- RAM 192 to 1024 bytes
- Programmable input/output ports 34
- High-breakdown-voltage output ports 28
- Software pull-up/pull-down resistors (P2₄-P2₇, P5₀-P5₅)
- Interrupts 14 sources, 13 vectors
- Timers 8-bit \times 6
- Serial I/O 8-bit \times 1 (Clock-synchronized)

- A-D converter 8-bit \times 8 channel
- Zero cross detection input 1 channel
- 2 Clock generating circuit
- Clock (X_{IN}-X_{OUT}) Internal feedback resistor
- Sub-clock (X_{CIN}-X_{COU}T) without internal feedback resistor
(connect to an external ceramic resonator or a quartz-crystal oscillator)
- Power source voltage
- In high-speed mode 4.0 to 5.5V
(at 6.3MHz oscillation frequency and high-speed selected)
- In middle-speed mode 2.8 to 5.5V
(at 6.3MHz oscillation frequency and middle-speed selected)
- In low-speed mode 2.8 to 5.5V
(at 32KHz oscillation frequency)
- Power dissipation
- In high-speed mode 38mW
(at 6.3MHz oscillation frequency)
- In low-speed mode 300 μ W
(at 32KHz oscillation frequency)
- Operating temperature range -10 to +85°C

APPLICATIONS

VCRs, tuners, musical instruments, office automation, etc.

PIN CONFIGURATION (TOP VIEW)

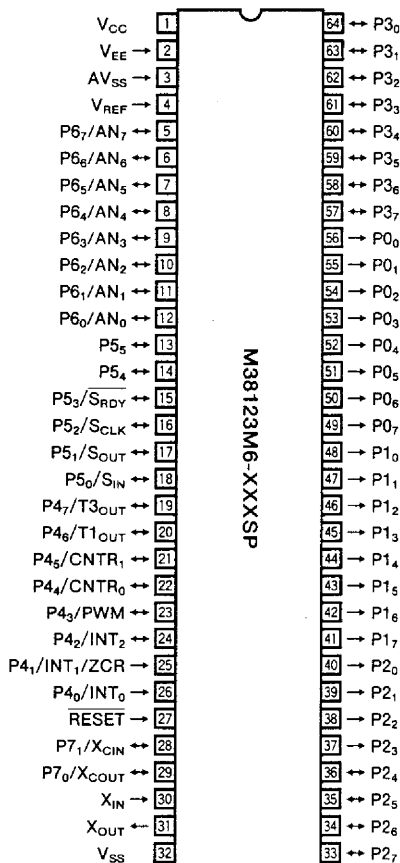


Package type : 64P6N-A

64-pin plastic-molded QFP

SINGLE-CHIP 8-BIT CMOS MICROCOMPUTER

PIN CONFIGURATION (TOP VIEW)



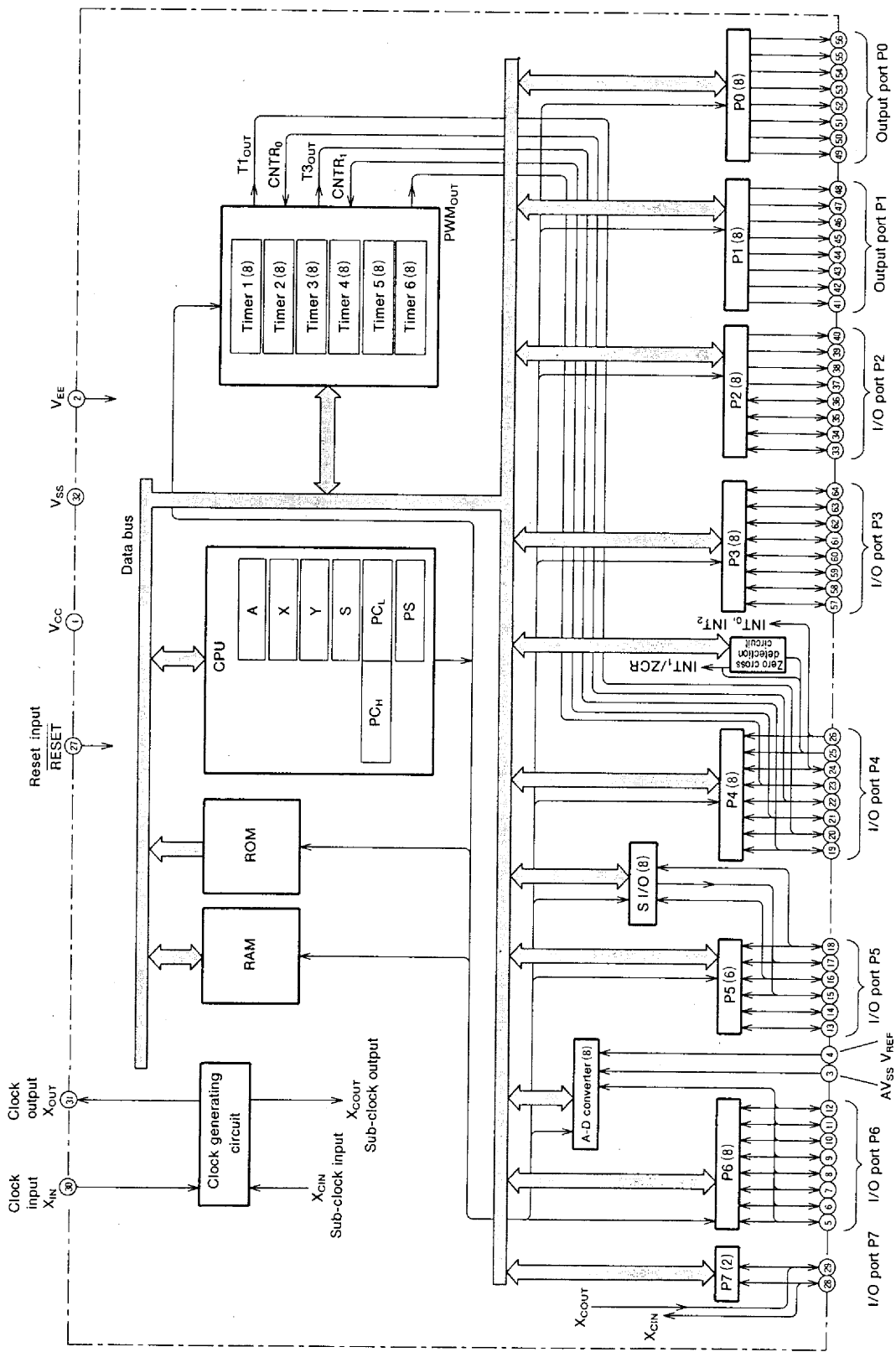
M38123M6-XXXXSP

Package type : 64P4B

64-pin shrink plastic-molded DIP

SINGLE-CHIP 8-BIT CMOS MICROCOMPUTER

FUNCTIONAL BLOCK DIAGRAM (Package : 64P4B)



SINGLE-CHIP 8-BIT CMOS MICROCOMPUTER

PIN DESCRIPTION

Pin	Name	Function	
			Function except a port function
V _{CC} , V _{SS}	Power source	• Apply voltage of 4.0 to 5.5V to V _{CC} , and 0V to V _{SS} .	
V _{EE}	Pull-down power source input	• Applies voltage supplied to pull-down resistors of ports P0, P1, and P2 ₀ -P2 ₃ .	
V _{REF}	Analog reference voltage	• Reference voltage input pin for A-D converter	
AV _{SS}	Analog power source	• Analog power source input pin for A-D converter • Connect AV _{SS} to V _{SS} .	
RESET	Reset input	• Reset input pin for active "L"	
X _{IN}	Clock input	• Input and output signals for the internal clock generating circuit. • Feedback resistor is built in between X _{IN} pin and X _{OUT} pin.	
X _{OUT}	Clock output	• Connect a ceramic resonator or a quartz-crystal oscillator between the X _{IN} and X _{OUT} pins to set the oscillation frequency. • If an external clock is used, connect the clock source to the X _{IN} pin and leave the X _{OUT} pin open. • This clock is used as the oscillating source of system clock.	
P0 ₀ -P0 ₇	Output port P0	• 8-bit output port • Each port builds in pull-down resistor between the output and the V _{EE} pin.	
P1 ₀ -P1 ₇	Output port P1	• The high-breakdown-voltage p-channel open-drain output • At reset these pins are set to the V _{EE} pin level.	
P2 ₀ -P2 ₃	Output port P2	• 4-bit output port with the same function as port P0.	
P2 ₄ -P2 ₇	I/O port P2	• 4-bit I/O port • I/O direction register allows each pin to be individually programmed as either input or output. • At reset this port is set to input mode. • Pull-up/pull-down register and I/O direction register allow each pin to be programmed as pull-down. • TTL input level • CMOS 3-state output	
P3 ₀ -P3 ₇	I/O port P3	• 8-bit I/O port with the same function as port P2 ₄ -P2 ₇ • CMOS compatible input level • The high-breakdown-voltage P-channel open-drain.	
P4 ₀ /INT ₀ , P4 ₁ /INT ₁ / ZCR	Input port P4	• 2-bit input port. • CMOS compatible input level	External interrupt input pins A zero cross detection circuit input pin (P4 ₁) A PWM output pin (Timer output pin) Timer 2, Timer 4 input pins Timer 1, Timer 3 output pins
P4 ₂ /INT ₂	I/O port P4	• 6-bit CMOS I/O port with the same function as port P2 ₄ -P2 ₇ • CMOS compatible input level • CMOS 3-state output	
P4 ₃ /PWM			
P4 ₄ /CNTR ₀ , P4 ₅ /CNTR ₁			
P4 ₆ /T1 _{OUT} , P4 ₇ /T3 _{OUT}			

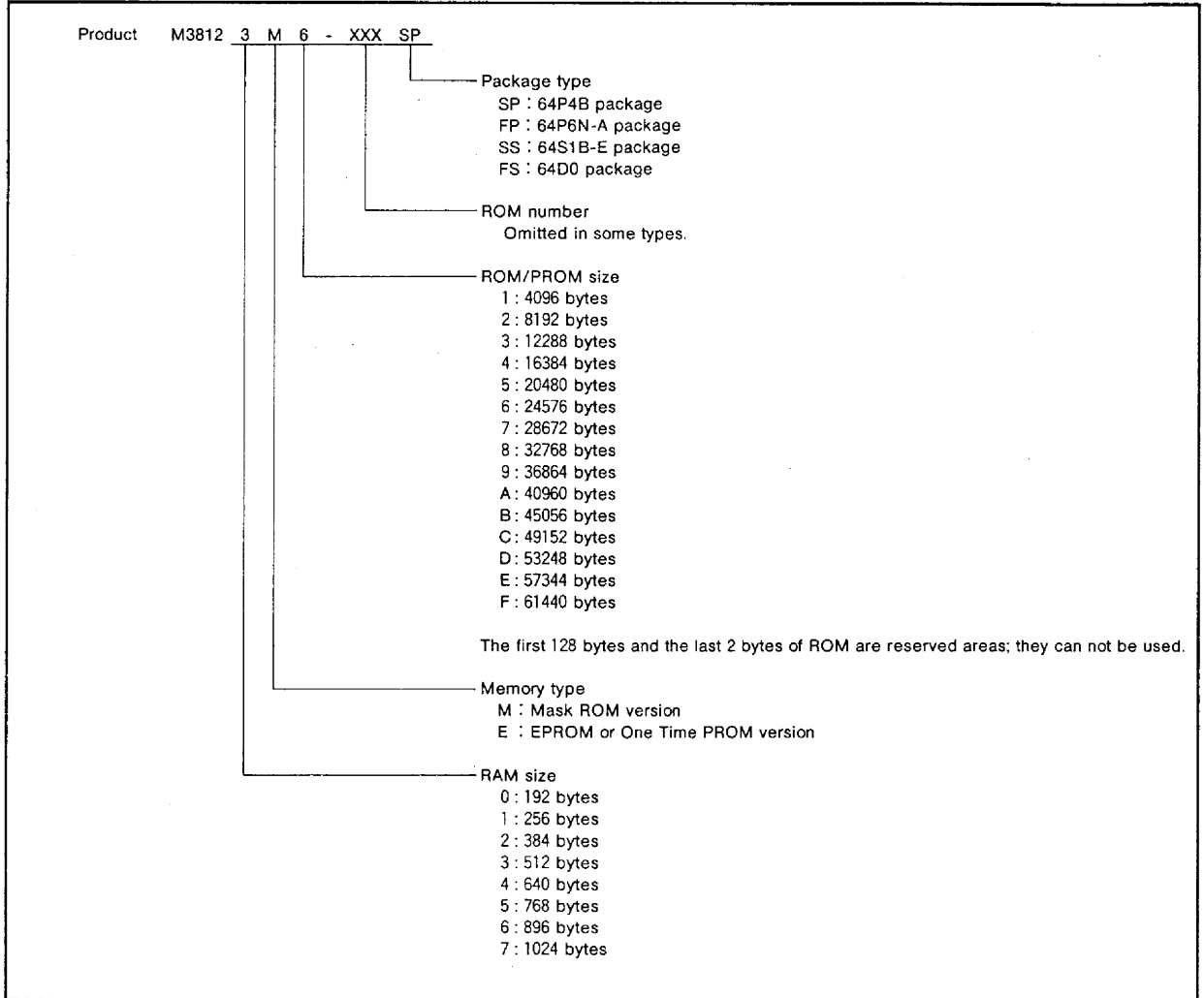
SINGLE-CHIP 8-BIT CMOS MICROCOMPUTER

PIN DESCRIPTION (Continued)

Pin	Name	Function	Function except a port function
P5 ₀ /S _{IN} , P5 ₁ /S _{OUT} , P5 ₂ /S _{CLK} , P5 ₃ /S _{RDY}	I/O port P5	<ul style="list-style-type: none"> 8-bit CMOS I/O port with the same function as port P2₄-P2₇ Keep the input voltage of this port between 0V and V_{CC}. The pull-up/pull-down register and I/O direction register allow each pin to be programmed as pull-up. CMOS compatible input level N-channel open-drain output 	Serial I/O pins
P5 ₄ , P5 ₅		<ul style="list-style-type: none"> 2-bit CMOS I/O port with the same function as port P2₄-P2₇ The pull-up/pull-down register and I/O direction register allow each pin to be programmed as pull-up. CMOS compatible input level CMOS 3-state output 	
P6 ₀ /AN ₀ - P6 ₇ /AN ₇	I/O port P6	<ul style="list-style-type: none"> 8-bit CMOS I/O port with the same function as port P2₄-P2₇ CMOS compatible input level CMOS 3-state output 	A-D converter input pins
P7 ₀ /X _{COU} , P7 ₁ /X _{CIN}	I/O port P7	<ul style="list-style-type: none"> 2-bit CMOS I/O port with the same function as port P2₄-P2₇ CMOS compatible input level CMOS 3-state output 	An I/O pin for the internal sub-clock generating circuit (connect a ceramic resonator or a quartz-crystal oscillator)

SINGLE-CHIP 8-BIT CMOS MICROCOMPUTER

PART NUMBERING



SINGLE-CHIP 8-BIT CMOS MICROCOMPUTER

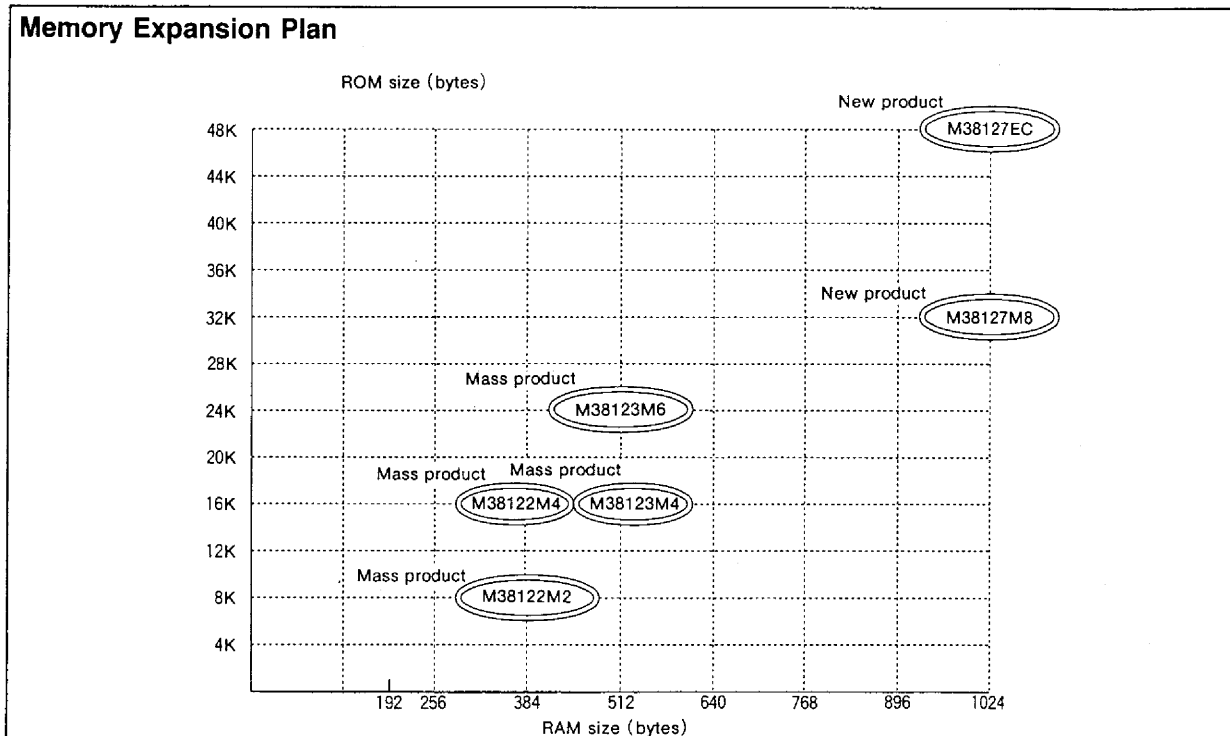
GROUP EXPANSION

Mitsubishi plans to expand the 3812 group as follows:

- (1) Support for mask ROM, One Time PROM, and EPROM versions
 - ROM/PROM size 8K to 48K bytes
 - RAM size 384 to 1024 bytes

(2) Packages

- 64P4B Shrink plastic molded DIP
- 64P6N-A Plastic molded QFP
- 64S1B-E Shrink ceramic DIP (EPROM version)
- 64D0 Ceramic LCC (EPROM version)



Currently supported products are listed below.

As of May 1996

Product	(P) ROM size (bytes) ROM size for User in ()	RAM size (bytes)	Package	Remarks
M38122M2-XXXSP	8192	384	64P4B	Mask ROM version
M38122M2-XXXFP	(8062)		64P6N-A	Mask ROM version
M38122M4-XXXSP	16384 (16254)		64P4B	Mask ROM version
M38122M4-XXXFP			64P6N-A	Mask ROM version
M38123M4-XXXSP		512	64P4B	Mask ROM version
M38123M4-XXXFP			64P6N-A	Mask ROM version
M38123M6-XXXSP	24576 (24446)		64P4B	Mask ROM version
M38123M6-XXXFP			64P6N-A	Mask ROM version
M38127M8-XXXSP		1024	64P4B	Mask ROM version
M38127M8-XXXFP			64P6N-A	Mask ROM version
M38127EC-XXXSP	64P4B		One Time PROM version	
M38127EC-XXXFP	64P6N-A		One Time PROM version	
M38127ECSP	49152 (49022)		64P4B	One Time PROM version (blank)
M38127ECFP			64P6N-A	One Time PROM version (blank)
M38127ECSS		64S1B-E	EPROM version	
M38127ECFS		64D0	EPROM version	

Renesas Technology Corp.

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- Mitsubishi Electric Corporation puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage. Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of non-flammable material or (iii) prevention against any malfunction or mishap.

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REVISION HISTORY	3812 GROUP USER'S MANUAL
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Rev.	Date	Description	
		Page	Summary
1.0	07/10/02		The first edition is issued.